

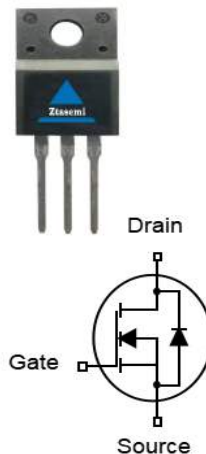
Features

- N-Channel
- Low Gate Charge
- 100% avalanche tested
- Low ON Resistance
- RoHS compliant
- Improved dv/dt Capability
- 100% EAS Tested

| | | |
|------------------------------|-----|----------|
| V_{DS} | 900 | V |
| $R_{DS(on),TYP}@ V_{GS}=10V$ | 1.2 | Ω |
| I_D | 9 | A |



| Part ID | Package Type | Marking | Packing |
|---------|--------------|---------|--------------|
| ZT9N90F | TO-220F | ZT9N90F | 1000pcs/Tape |

TO-220F


Absolute Maximum Ratings $T_A=25^\circ\text{C}$, unless otherwise specified

| Symbol | Parameter | Rating | Unit | |
|--|---|------------------------------|------------------|---------------------------|
| Common Ratings ($T_c=25^\circ\text{C}$ Unless Otherwise Noted) | | | | |
| V_{GS} | Gate-Source Voltage | ± 30 | V | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | 900 | V | |
| T_J | Maximum Junction Temperature | 150 | $^\circ\text{C}$ | |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ | |
| I_{DM} | Drain Current-Continuous@ Current-Pulsed (Note 2) | $T_c=25^\circ\text{C}$ 36 | A | |
| Mounted on Large Heat Sink | | | | |
| I_D | Drain Current-Continuous (Note 1) | $T_c=25^\circ\text{C}$ | 9 | A |
| | | $T_c=100^\circ\text{C}$ | 5.6 | A |
| P_D | Total power dissipation | $T_c=25^\circ\text{C}$ | 25 | W |
| | Derating Factor above 25°C | | 0.2 | W/ $^\circ\text{C}$ |
| $R_{\theta JC}$ | Thermal Resistance-Junction to Case | | 5 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | | 69 | $^\circ\text{C}/\text{W}$ |
| Drain-Source Avalanche Ratings | | | | |
| EAS | Avalanche Energy, Single Pulsed (Note 3) | | 486 | mJ |
| dv/dt | Reverse Diode dv/dt (Note 4) | | 5 | V/ns |

Electrical Characteristics (T_J=25°C unless otherwise noted)

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|-----|------|------|------|
| Static Electrical Characteristics @ T_J=25°C (unless otherwise stated) | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 900 | -- | -- | V |
| BV _{DSS} /T _J | Breakdown voltage temperature coefficient | I _D =250μA, referenced to 25°C | -- | 0.82 | -- | V/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =900V, V _{GS} =0V | -- | -- | 1 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =±30V, V _{DS} =0V | -- | -- | ±100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 3.0 | 4.0 | 5.0 | V |
| R _{DS(on)} | Drain-Source On-State Resistance | V _{GS} =10V, I _D =4.5A | -- | 1.2 | 1.5 | Ω |
| G _{fs} | Forward Transconductance | V _{GS} =10V, I _D =4.5A | -- | 7.2 | -- | S |
| Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated) | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} =25V, V _{GS} =0V, f=1MHz | -- | 2050 | -- | pF |
| C _{oss} | Output Capacitance | | -- | 144 | -- | pF |
| C _{rss} | Reverse Transfer Capacitance | | -- | 11 | -- | pF |
| R _g | Gate Resistance | V _{DS} = 0V Scan F mode | -- | 2.3 | -- | Ω |
| Q _g | Total Gate Charge | V _{DS} =720V, I _D =9A, V _{GS} =10V | -- | 42.1 | -- | nC |
| Q _{gs} | Gate-Source Charge | | -- | 13.1 | -- | nC |
| Q _{gd} | Gate-Drain Charge | | -- | 18.6 | -- | nC |
| Switching Characteristics (Note 2) | | | | | | |
| T _{d(on)} | Turn-on Delay Time | V _{DS} =450V, I _D = 9A, R _G =25Ω, V _{GS} =10V | -- | 49 | -- | ns |
| T _r | Turn-on Rise Time | | -- | 64 | -- | ns |
| T _{d(off)} | Turn-Off Delay Time | | -- | 85 | -- | ns |
| T _f | Turn-Off Fall Time | | -- | 33 | -- | ns |
| Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated) | | | | | | |
| V _{SD} | Forward on voltage | I _S =9A, V _{GS} =0V | -- | -- | 1.3 | V |
| T _{rr} | Reverse Recovery Time | T _J =25°C, I _S = 9A, V _{GS} = 0V, di/dt=100A/μs | -- | 656 | -- | ns |
| Q _{rr} | Reverse Recovery Charge | | -- | 9.2 | -- | μC |
| I _{rrm} | Peak Reverse Recovery Current | | -- | 28 | -- | A |

Notes

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
3. L = 12mH, I_{AS} = 9A, V_{DD} = 50V, R_G=25Ω, Starting at T_J = 25°C
4. I_{SD} ≤ I_D, di/dt = 100A/μs, V_{DD} ≤ BV_{DSS}, Starting at T_J = 25°C

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

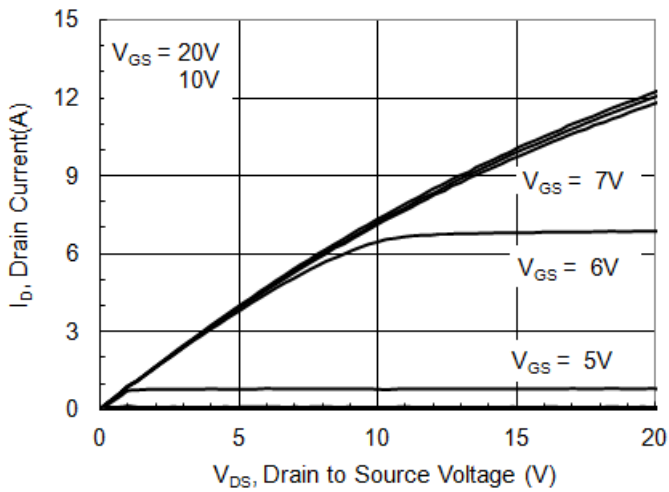


Fig1. Output characteristics

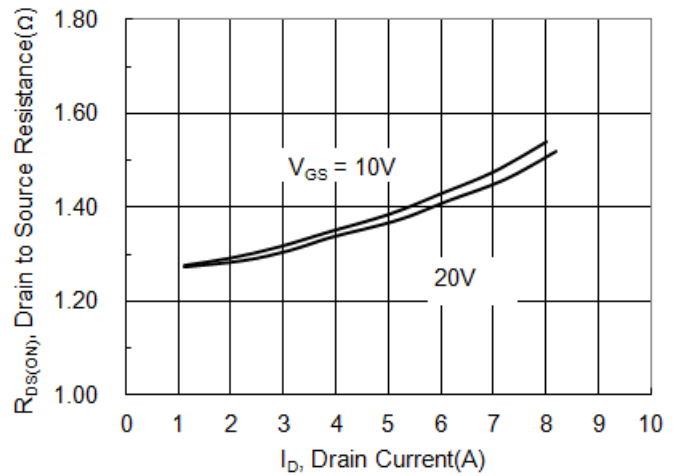


Fig4. Drain-source on-state resistance

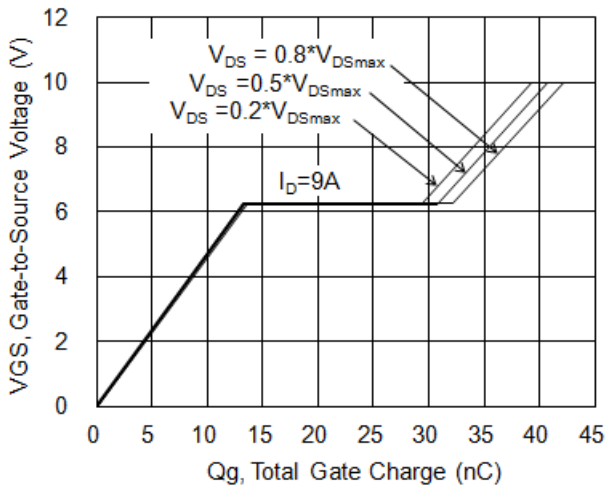


Fig2. Gate charge characteristics

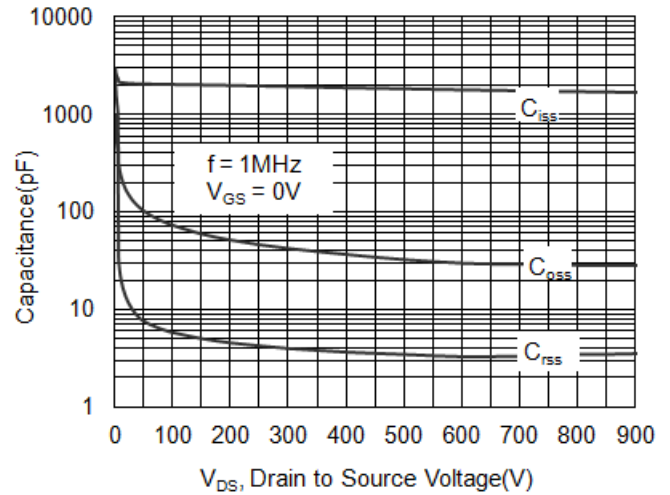


Fig 5. Capacitance Characteristics

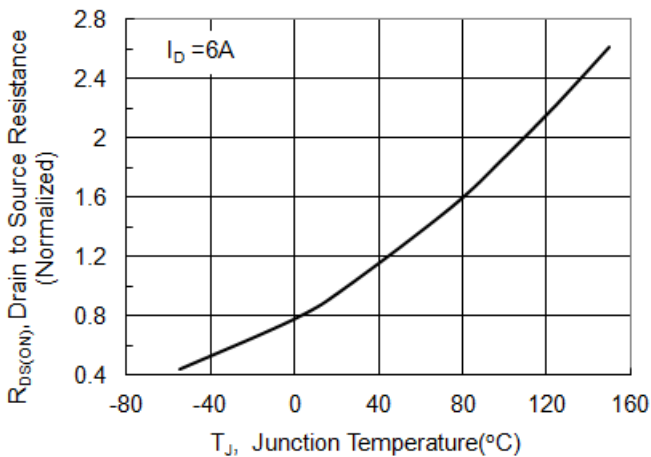


Fig 3. $R_{DS(ON)}$ vs junction temperature

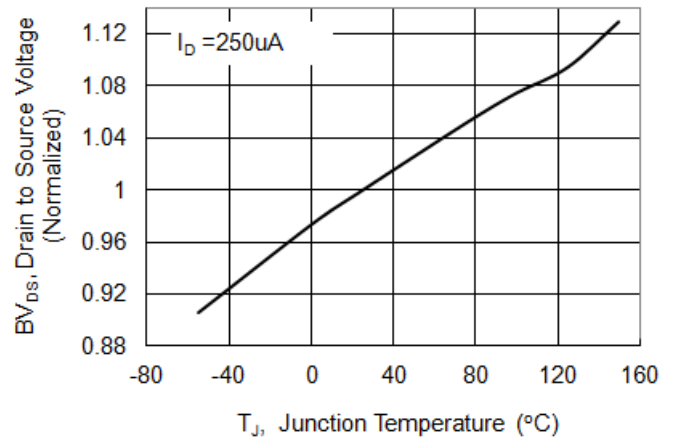


Fig 6. BV_{bss} vs junction temperature

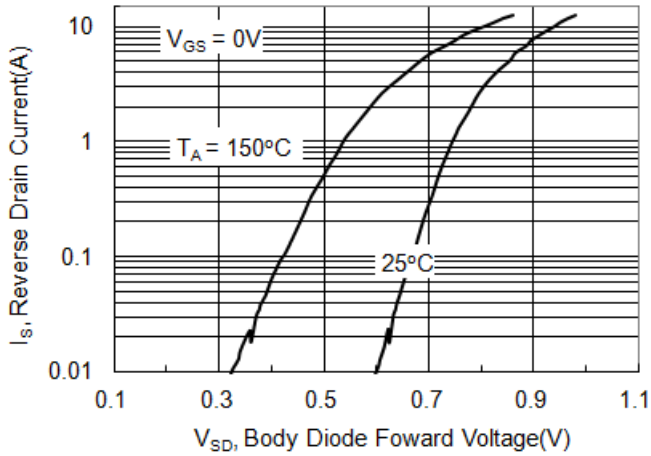


Fig 7. Forward characteristics of reverse diode

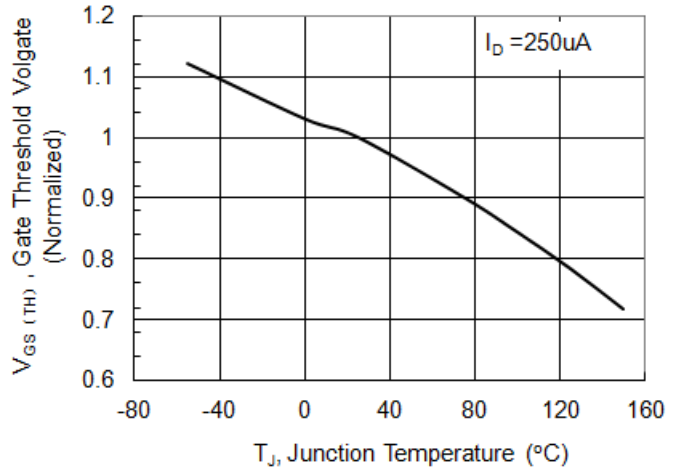


Fig 9. $V_{GS(TH)}$ vs junction temperature

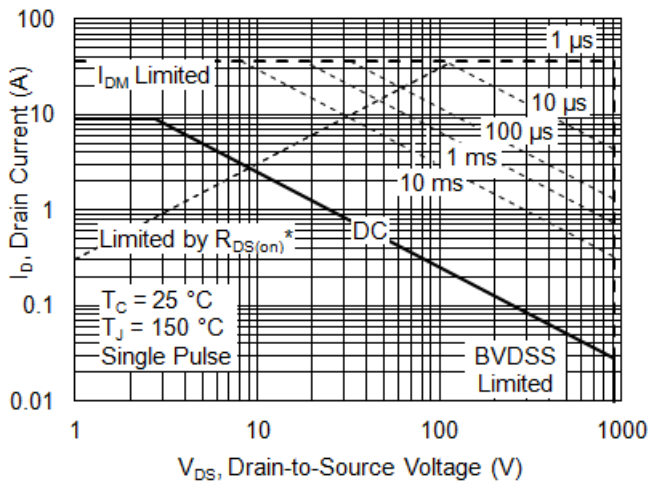


Fig 8 . Safe operating area (TO-220F)

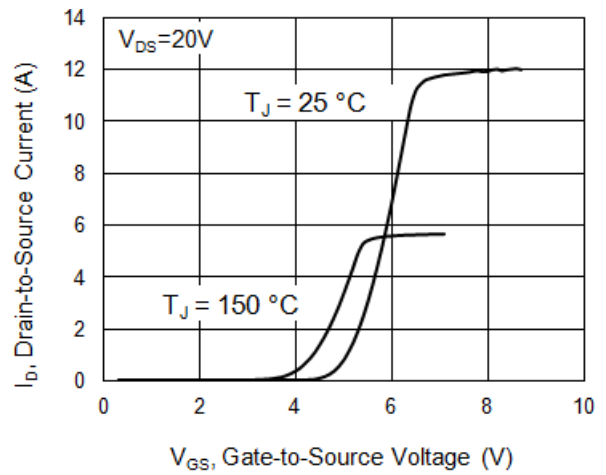


Fig 10. Transfer characteristics

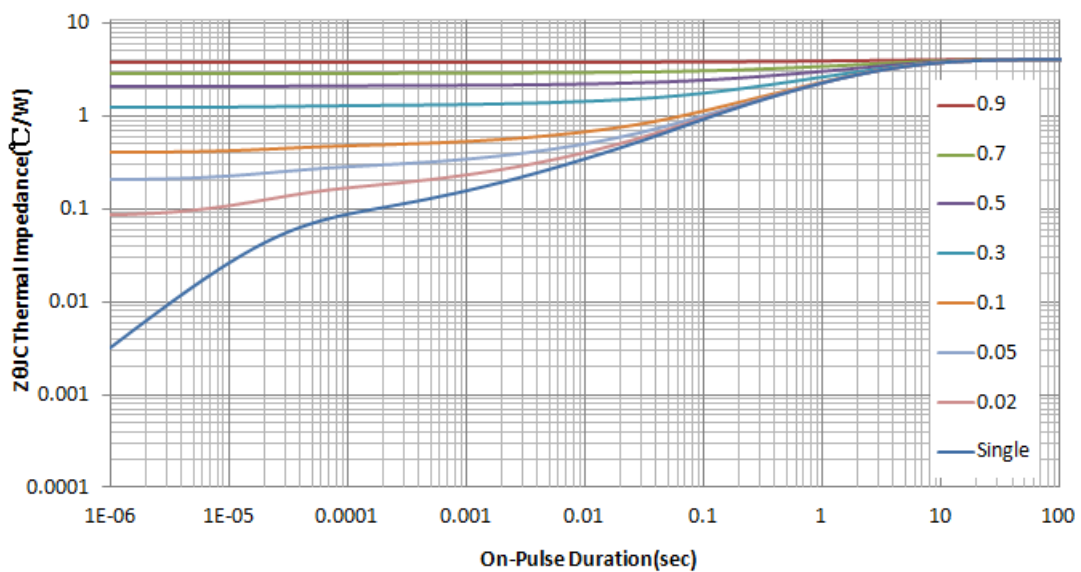


Fig 11 . Transient thermal impedance(TO-220F)

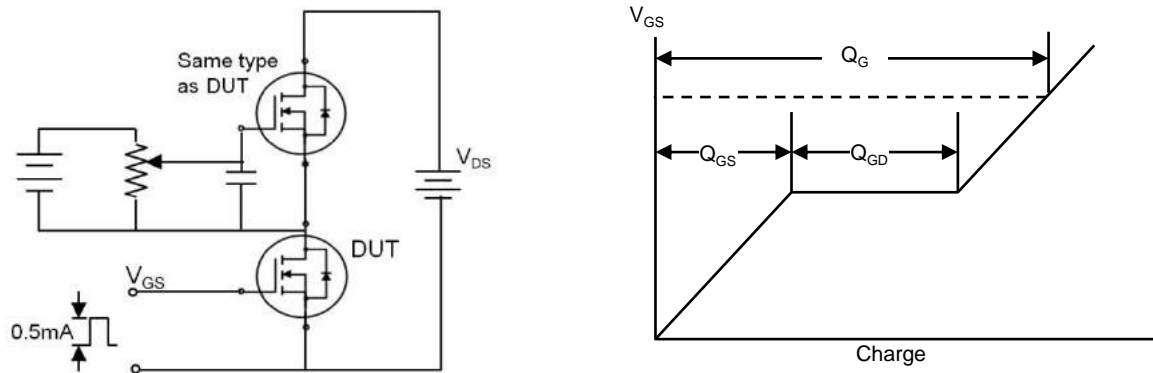


Figure A: Gate charge test circuit & waveform

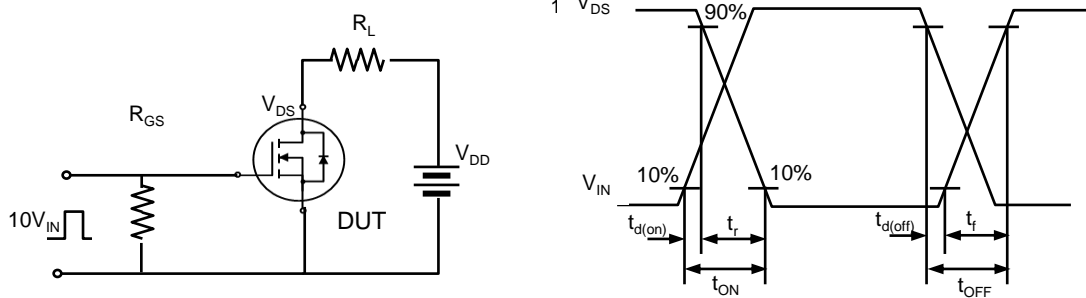


Figure B: Switching time test circuit & waveform

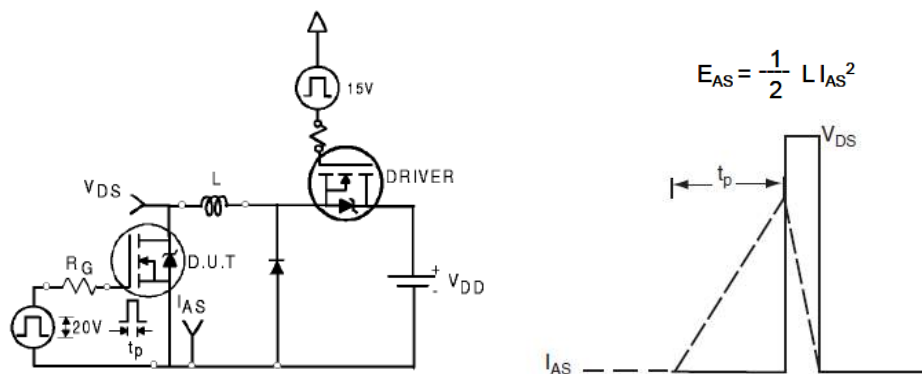


Figure C: Unclamped Inductive switching test circuit & waveform

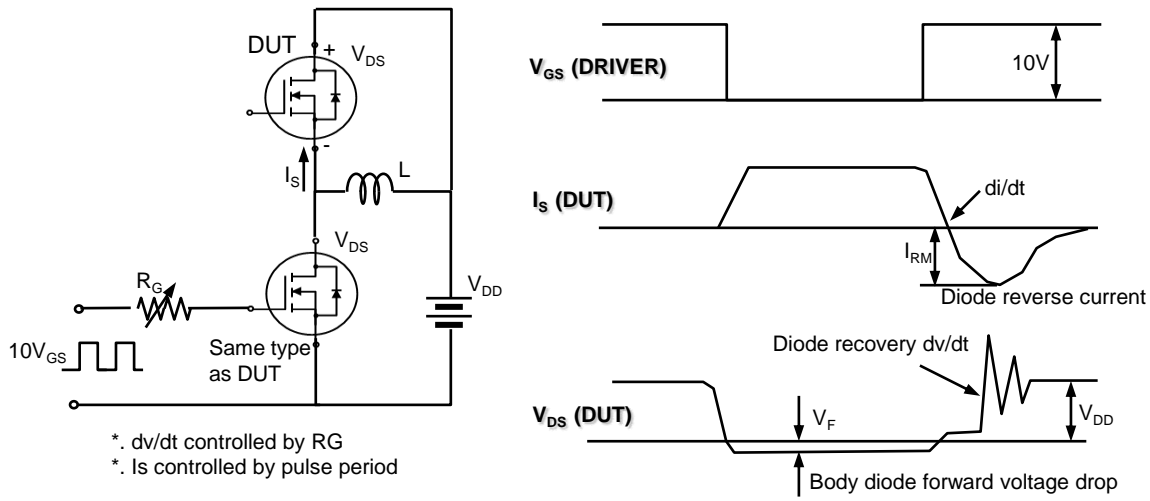
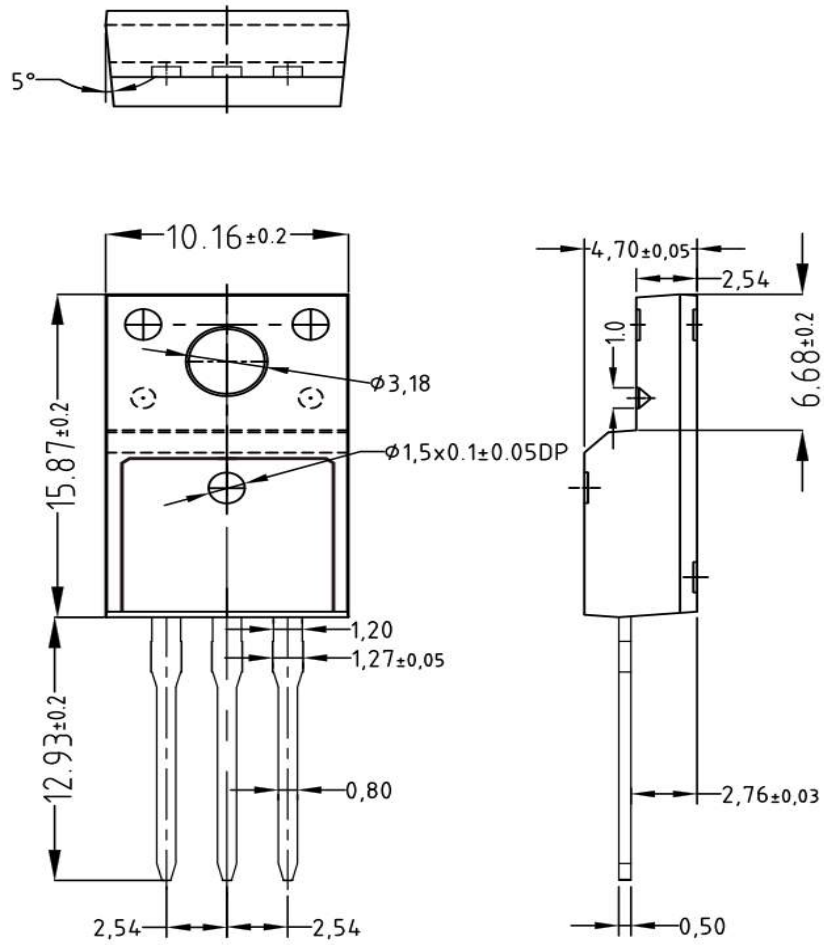


Figure D: Peak diode recovery dv/dt test circuit & waveform

TO-220F Package Information



Customer Service

Sales and Service:

zj@ztasemi.com